

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RAJENDRA D. PENDSE	07/08/2020
RECEIVING PARTY DATA	
Name:	META PLATFORMS TECHNOLOGIES, LLC
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18062409
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NAME OF SUBMITTER:	AHSAN A. SHAIKH, REG. NO. 61861
SIGNATURE:	/Ahsan A. Shaikh/
DATE SIGNED:	11/08/2023
Total Attachments: 2	
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COMBINED ASSIGNMENT/DECLARATION (37 CFR 1.63)

For good and valuable consideration, the receipt of which is hereby acknowledged, the person(s) named below (referred to as "INVENTOR" whether singular or plural) has sold, assigned, and transferred and does hereby sell, assign, and transfer to **Facebook Technologies, LLC**, a Delaware corporation, having a place of business at 1601 Willow Road, Menlo Park, California 94025 ("ASSIGNEE"), for itself and its successors, transferees, and assignees, the following:

1. The entire worldwide right, title, and interest in all inventions and improvements ("SUBJECT MATTER") that are disclosed in the following provisional application filed under 35 U.S.C. § 111(b), non-provisional application filed under 35 U.S.C. § 111(a), international application filed according to the Patent Cooperation Treaty (PCT), or U.S. national phase application filed under 35 U.S.C. § 371 ("APPLICATION"):

Application No. 16/910,792, entitled "ARTIFICIAL REALITY SYSTEM HAVING SYSTEM-ON-A-CHIP (SoC) INTEGRATED CIRCUIT COMPONENTS INCLUDING STACKED SRAM" filed on : June 24, 2020.

2. The entire worldwide right, title, and interest in and to:
(a) the APPLICATION; (b) all applications claiming priority from the APPLICATION; (c) all provisional, utility, divisional, continuation, substitute, renewal, reissue, and other applications related thereto which have been or may be filed in the United States or elsewhere in the world; (d) all patents (including reissues and re-examinations) which may be granted on the applications set forth in (a), (b), and (c) above; and (e) all right of priority in the APPLICATION and in any underlying provisional or foreign application, together with all rights to recover damages for infringement of provisional rights.

INVENTOR agrees that ASSIGNEE may apply for and receive patents for SUBJECT MATTER in ASSIGNEE's own name.

INVENTOR agrees to do the following, when requested, and without further consideration, in order to carry out the intent of this Assignment: (1) execute all oaths, assignments, powers of attorney, applications, and other papers necessary or desirable to fully secure to ASSIGNEE the rights, titles and interests herein conveyed; (2) communicate to ASSIGNEE all known facts relating to the SUBJECT MATTER; and (3) generally do all lawful acts that ASSIGNEE shall consider desirable for securing, maintaining, and enforcing worldwide patent protection relating to the SUBJECT MATTER and for vesting in ASSIGNEE the rights, titles, and interests herein conveyed. INVENTOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE hereunder.

INVENTOR represents that INVENTOR has the rights, titles, and interests to convey as set forth herein, and covenants with ASSIGNEE that the INVENTOR has not made and will not hereafter make any assignment, grant, mortgage, license, or other agreement affecting the rights, titles, and interests herein conveyed.

INVENTOR grants the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Title: ARTIFICIAL REALITY SYSTEM
HAVING SYSTEM-ON-A-CHIP (SoC)
INTEGRATED CIRCUIT COMPONENTS
INCLUDING STACKED SRAM

Date Filed: June 24, 2020

Application No.: 16/910,792

This Assignment may be executed in one or more counterparts, each of which shall be deemed an original and all of which may be taken together as one and the same Assignment.

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76)**

By signing below, INVENTOR further attests to the following:

- The APPLICATION was made or authorized to be made by INVENTOR.
- INVENTOR believes that INVENTOR is the original inventor or an original joint inventor of a claimed invention in the APPLICATION.
- INVENTOR acknowledges the duty to disclose to the United States Patent and Trademark Office all information known to INVENTOR to be material to patentability as defined in 37 CFR § 1.56, which for a continuation-in-part includes information known to INVENTOR to be material to patentability as defined in 37 CFR § 1.56 that became available between the filing date of the prior patent application and the National or PCT filing date of the continuation-in-part application.

INVENTOR hereby acknowledges that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Name and Signature


Rajendra D. Pendse (Jul 8, 2020 12:28 PM)

Dr. Rajendra D. Pendse

Date of Signature

Jul 8, 2020